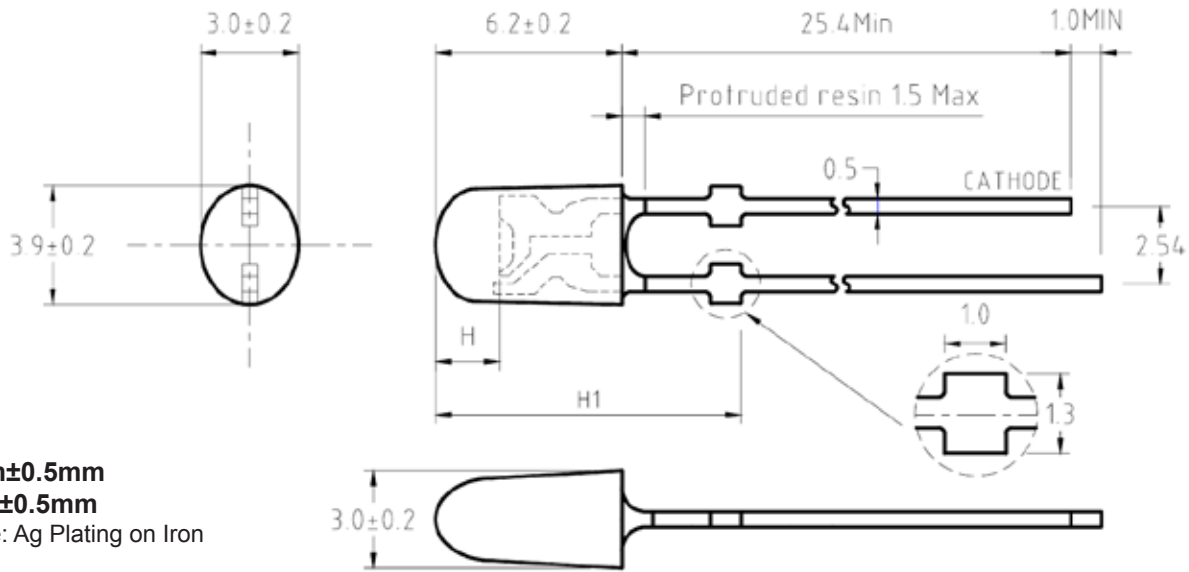


**SPECIFICATIONS**
**CLV43SR2DS-70**
**OUTLINES DIMENSIONS / Lamps with Standoffs**


**H=1.75mm±0.5mm**  
**H1=10mm±0.5mm**  
 Lead Frame: Ag Plating on Iron

**Notes:**

1. All Dimensions are in millimeters (inches).
2. Tolerance is  $\pm 0.25 \text{ mm}$  ( $0.01''$ ) unless otherwise noted.
3. Specifications are subject to change without notice.

**Luminous Intensity Bin Table**

IF=20mA		
Rank Name	Min (mcd)	Max (mcd)
R	1500	1900
S	1900	2500
T	2500	3200

\* Tolerance for each bin limit is  $\pm 15\%$

**Color Bin Table**

IF=20mA		
Rank Name	Min (mcd)	Max (mcd)
1	615	620
2	620	625
3	625	630
4	630	635

\* Tolerance for each bin limit is  $\pm 1 \text{ nm}$

Part Number	Chip Material	Color of Emission	Lens Type	Viewing Angle
CLV43SR2DS-70	AllnGaP	Red	Epoxy Resin	70/40°



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**ABSOLUTE MAXIMUM RATINGS**
**(TA=25°C)**

Parameter	Symbol	Max Rating	Unit
Power Dissipation	$P_D$	120	mW
Pulse Current Forward Current	$I_{FP}$	100	mA
Continuous Forward Current	$I_F$	50	mA
Reverse Voltage	$V_R$	5.0	V
Operating Temperature Range	$T_{OPR}$	-30 ~ +85	°C
Storage Temperature Range	$T_{STG}$	-40 ~ +100	°C

 $I_{FP}$  = Pulse Width  $\leq$  10 ms, Duty Ratio  $\leq$  1/10.      Soldering Condition: 260 °C/ 5sec

\* $I_{FP}$  = Pulse Width  $\leq$  10ms, Duty Ratio  $\leq$  1/10

**OPTICAL-ELECTRICAL CHARACTERISTICS**
**(TA=25°C)**

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Luminous Intensity	$I_V$	$I_F = 20\text{mA}$	1500	2000		mcd
Forward Voltage	$V_F$	$I_F = 20\text{mA}$		2.1	2.4	V
Reverse Leakage Current	$I_R$	$V_R = 5\text{V}$			50	$\mu\text{A}$
Viewing Angle	$2\theta_{1/2}$	$I_F = 20\text{mA}$		70/40°		deg.
Peak Wavelength	$\lambda_P$	$I_F = 20\text{mA}$		635		nm
Dominant Wavelength	$\lambda_D$	$I_F = 20\text{mA}$	615	625	635	nm
Spectral Line half-width	$\Delta\lambda$	$I_F = 20\text{mA}$		15		nm

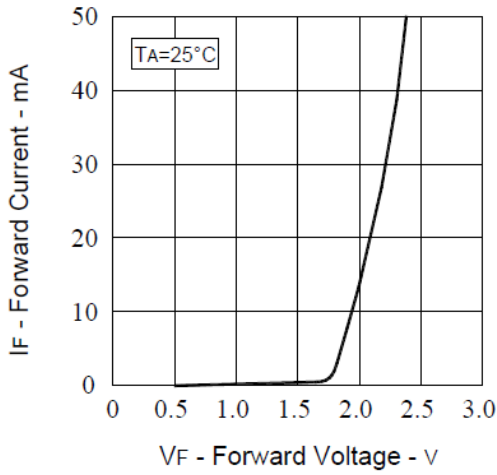
\*Tolerance of viewing angle: -10 / +5 deg.



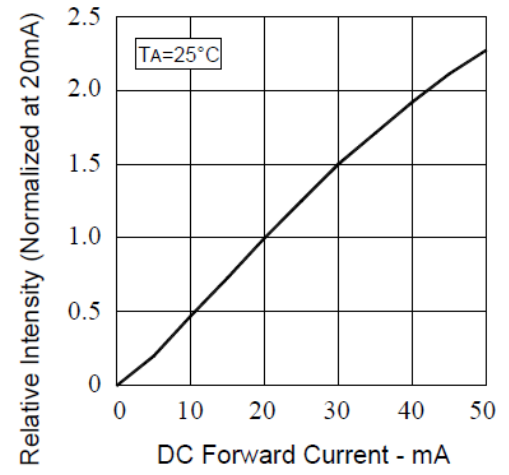
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## OPTICAL CHARACTERISTIC CURVES

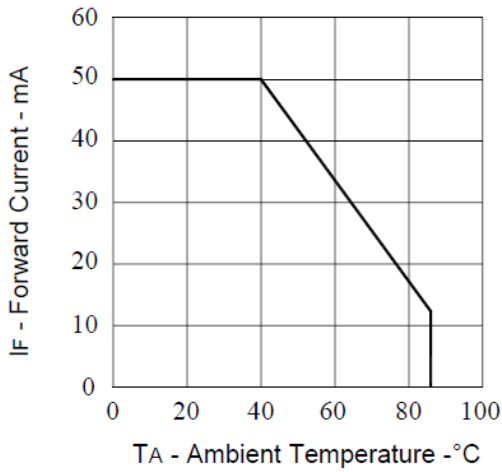
Forward Current vs. Forward Voltage



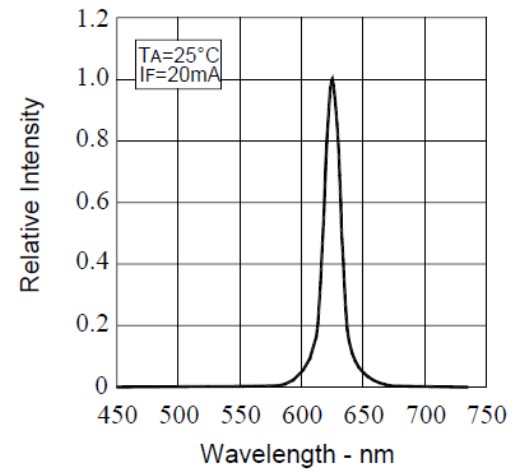
Relative Intensity vs. Forward Current



Forward Current vs. Ambient Temperature



Relative Intensity vs. Wavelength



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## SOLDERING CONDITIONS – LAMP TYPE LED

\* Solder the LED no closer than 3mm from the base of the epoxy bulb. Soldering beyond the base of the tie bar is recommended.

\* Recommended soldering conditions

Dip Soldering	
Pre-Heat	100 °C Max
Pre-Heat Time	60 Second Max
Solder Bath Temperature	260 °C Max
Dipping Time	5 Second Max
Dipping Position	No lower than 3mm from the base of the epoxy

Hand Soldering		
	3mm Series	Others
Temperature Soldering Time Position	300 °C Max 3 Second Max No closer than 3mm from the base of the epoxy	350 °C Max 3 Second Max No closer than 3mm from the base of the epoxy

\* Do not apply any stress to the lead. Particularly when heated.

\* The LED must not be repositioned after soldering.

\* After soldering the LEDs, the epoxy bulb should be protected from mechanical shock or vibration until the LEDs return to room temperature.

\* Direct soldering onto a PC board should be avoided. Mechanical stress to the resin may be caused by the PC board warping or from the clinching and cutting of the leadframes. When it is absolutely necessary, the LEDs may be mounted in this fashion, but, the user will assume responsibility for any problems. Direct soldering should only be done after testing has confirmed that no damage, such as wire bond failure or resin deterioration, will occur. LEDs should not be soldered directly to double sided PC boards because the heat will deteriorate the epoxy resin.

\* When it is necessary to clamp the LEDs to prevent soldering failure, it is important to minimize the mechanical stress on the LEDs.

\* Cut the LED leadframes at room temperature. Cutting the leadframes at high temperature may cause LED failure.



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